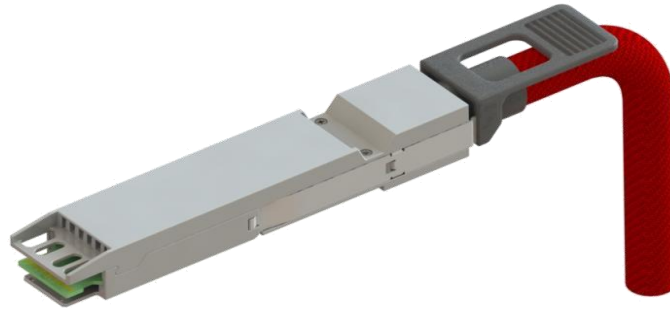


1.6T OSFP1600 TO OSFP1600 Active Direct Attached Cable



FEATURES

- Module compliant to OSFP MSA
- Transmission data rate up to PAM4 212.5Gbps per channel
- Low power consumption
- Linear PAM4 programmable equalizer optimized for 112GBaud copper link up to max length 3M on 26AWG
- Enable Auto-Negotiation and Link Training
- Supports device programming by MCU with I2C
- Power supply 3.3V
- Operating case temperature 0°C to +70°C
- RoHS2.0 compliant

Absolute Maximum Ratings

Parameter	Symbol	Min	Typical	Max	Unit
Supply Voltage	V _{CC}	-0.3	3.3	3.6	V
Storage temperature	T _S	-40		85	°C
Operating Case temperature	T _C	0		70	°C
Humidity	Rh	5		85	%
Data Rate			1600		Gbps

Physical Characteristics

Parameter	Symbol	Min	Typical	Max	Unit
Length	L	1		3	M
AWG		28		26	AWG
Jacket material		HAIRTAIL Net			

Electrical Specifications

Parameter	Symbol	Min	Typical	Max	Unit
Power supply voltage	V _{CC}	3.1	3.3	3.5	V
Input LOW Voltage	V _{IL}	-0.3		0.35*V _{CC}	V
Input HIGH Voltage	V _{IH}	0.65* V _{CC}		V _{CC} +0.3	V
Output Logic LOW	V _{OL}			0.25* V _{CC}	V
I2C Master Mode Output Frequency			400		kHz
800G end Power consumption			1.2	1.5	W

High-Speed Specifications

Parameter	Symbol	Min	Typical	Max	Unit
Raw cable impedance	Zca	90	95	100	ohm
Mated connector Impedance	Zmated	85		110	ohm
Maximum insertion loss at 53.125GHz	SDD21			34	dB
Minimum cable assembly ERL	ERL	8.25			dB
BER				E-8	

Pin Description

Top Side (viewed from top)

60	GND	
59	TX1p	
58	TX1n	
57	GND	
56	TX3p	
55	TX3n	
54	GND	
53	TX5p	
52	TX5n	
51	GND	
50	TX7p	
49	TX7n	
48	GND	
47	SDA	
46	VCC	
45	VCC	
44	INT/RSTn	
43	GND	
42	RX8n	
41	RX8p	
40	GND	
39	RX6n	
38	RX6p	
37	GND	
36	RX4n	
35	RX4p	
34	GND	
33	RX2n	
32	RX2p	
31	GND	

Bottom Side (viewed from bottom)

	GND	1
	TX2p	2
	TX2n	3
	GND	4
	TX4p	5
	TX4n	6
	GND	7
	TX6p	8
	TX6n	9
	GND	10
	TX8p	11
	TX8n	12
	GND	13
	SCL	14
	VCC	15
	VCC	16
	LPWn/PRSn	17
	GND	18
	RX7n	19
	RX7p	20
	GND	21
	RX5n	22
	RX5p	23
	GND	24
	RX3n	25
	RX3p	26
	GND	27
	RX1n	28
	RX1p	29
	GND	30

----- Module Card Edge -----

Electrical Pin-out Details for OSFP

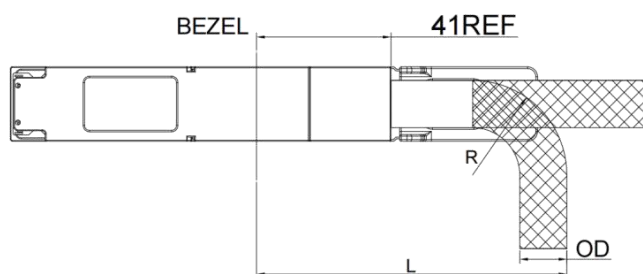
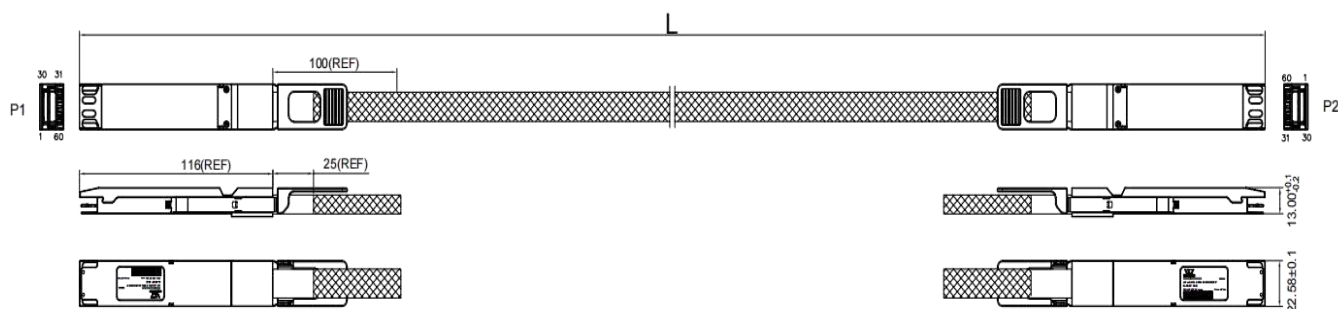
Pin#	Symbol	Description	Logic	Direction	Plug Sequence	Notes
1	GND	Ground			1	
2	TX2p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
3	TX2n	Transmitter Data Inverted	CML-I	Input from Host	3	
4	GND	Ground			1	
5	TX4p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
6	TX4n	Transmitter Data Inverted	CML-I	Input from Host	3	
7	GND	Ground			1	
8	TX6p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
9	TX6n	Transmitter Data Inverted	CML-I	Input from Host	3	
10	GND	Ground			1	
11	TX8p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
12	TX8n	Transmitter Data Inverted	CML-I	Input from Host	3	
13	GND	Ground			1	
14	SCL	2-wire Serial interface clock	LVC MOS-I/O	Bi-directional	3	Open-Drain with pull-up resistor on Host
15	VCC	+3.3V Power		Power from Host	2	
16	VCC	+3.3V Power		Power from Host	2	
17	LPWn/PRSn	Low-Power Mode / Module Present	Multi-Level	Bi-directional	3	See pin description for required circuit
18	GND	Ground			1	
19	RX7n	Receiver Data Inverted	CML-O	Output to Host	3	
20	RX7p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
21	GND	Ground			1	
22	RX5n	Receiver Data Inverted	CML-O	Output to Host	3	
23	RX5p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
24	GND	Ground			1	
25	RX3n	Receiver Data Inverted	CML-O	Output to Host	3	
26	RX3p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
27	GND	Ground			1	
28	RX1n	Receiver Data Inverted	CML-O	Output to Host	3	
29	RX1p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
30	GND	Ground			1	

Pin#	Symbol	Description	Logic	Direction	Plug Sequence	Notes
31	GND	Ground			1	
32	RX2p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
33	RX2n	Receiver Data Inverted	CML-O	Output to Host	3	
34	GND	Ground			1	
35	RX4p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
36	RX4n	Receiver Data Inverted	CML-O	Output to Host	3	
37	GND	Ground			1	
38	RX6p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
39	RX6n	Receiver Data Inverted	CML-O	Output to Host	3	
40	GND	Ground			1	
41	RX8p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
42	RX8n	Receiver Data Inverted	CML-O	Output to Host	3	
43	GND	Ground			1	
44	INT/RSTn	Module Interrupt / Module Reset	Multi-Level	Bi-directional	3	See pin description for required circuit
45	VCC	+3.3V Power		Power from Host	2	
46	VCC	+3.3V Power		Power from Host	2	
47	SDA	2-wire Serial interface data	LVC MOS-I/O	Bi-directional	3	Open-Drain with pull-up resistor on Host
48	GND	Ground			1	
49	TX7n	Transmitter Data Inverted	CML-I	Input from Host	3	
50	TX7p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
51	GND	Ground			1	
52	TX5n	Transmitter Data Inverted	CML-I	Input from Host	3	
53	TX5p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
54	GND	Ground			1	
55	TX3n	Transmitter Data Inverted	CML-I	Input from Host	3	
56	TX3p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
57	GND	Ground			1	
58	TX1n	Transmitter Data Inverted	CML-I	Input from Host	3	
59	TX1p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
60	GND	Ground			1	

Module Memory Map

Compatible with CMIS rev 5.0 or further CMIS revisions and customer spec.

Mechanical Dimensions



OSFP TYPE2			
GAUGE	OD	BEND RADIUS "R"	MIN. BEND RADIUS "L"
28AWG	10.2MM	21MM	81MM
26AWG	12.1MM	25MM	86MM

Ordering Information

Model Number Part Number	Description
POOP16CP5	1.6T OSFP1600 to OSFP1600 Active DAC, 0.5M, 28AWG
POOP16C01	1.6T OSFP1600 to OSFP1600 Active DAC, 1.0M, 28/26AWG
POOP16C1P5	1.6T OSFP1600 to OSFP1600 Active DAC, 1.5M, 28/26AWG
POOP16C02	1.6T OSFP1600 to OSFP1600 Active DAC, 2.0M, 28/26AWG
POOP16C03	1.6T OSFP1600 to OSFP1600 Active DAC, 3.0M, 26AWG

References

1. IEEE802.3dj
2. OSFP MSA Rev5.0
3. Common Management Interface Specification (CMIS) Rev5.0

Revision Records

REV.	Description	Designed	Checked	Approved	Issue Date
X1	Preliminary	XICHUN TAN	XICHUN TAN	RYAN LEI	2023.12.18